



## Lenovo 4XB7A79646 internal solid state drive 960 GB M.2 PCI Express 4.0 NVMe 3D TLC NAND



**Brand :** Lenovo

**Product code:** 4XB7A79646

**Product name :** 4XB7A79646

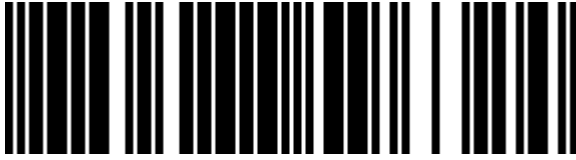
ThinkSystem 2.5" U.3 7450 PRO 960GB Read Intensive NVMe PCIe 4.0 x4 HS SSD

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The ThinkSystem 7450 PRO Read Intensive NVMe SSDs are general-purpose yet high-performance family of NVMe solid-state drives. They are engineered for greater performance and endurance in a cost-effective design, and to support a broader set of workloads. Now with SED encryption as standard, these drives help ensure data security, even when the drive is removed from the server.

This product guide provides essential presales information to understand the ThinkSystem 7450 PRO Read Intensive NVMe SSDs offerings and their key features, specifications, and compatibility. This guide is intended for technical specialists, sales specialists, sales engineers, IT architects, and other IT professionals who want to learn more about the 7450 PRO SSDs and consider their use in IT solutions Lenovo 4XB7A79646. SSD capacity: 960 GB, SSD form factor: M.2, Component for: Server/workstation

Features		Features	
SSD capacity *	960 GB	Certification	CE (Europe): EN55032, EN55024 Class B, RoHS FCC: CFR Title 47, Part 15, Class B UL/cUL: approval to UL-60950-1, 2nd Edition, IEC 60950-1:2005 (2nd Edition); EN 60950-1 (2006) + A11:2009+ A1:2010 + A12:2011 + A2:2013
SSD form factor *	M.2		BSMI (Taiwan): approval to CNS 13438, Class B, CNS 15663 RCM (Australia, New Zealand): AS/NZS CISPR32 Class B KC RRL (Korea): approval to KN32 Class B, KN 35 Class B W.E.E.E.: Compliance with EU WEEE directive 2012/19/EC. TUV (Germany): approval to IEC60950/EN60950 VCCI (Japan): 2015-04 Class B IC (Canada): ICES-003 Class B Morocco: EN55032, EN55024 Class B UkrSEPRO (Ukraine): EN55032 Class B, IEC60950/EN60950, RoHS (Resolution 2017 No. 139) UKCA (UK): SI 2016/1091 Class B and SI 2012/3032 RoHS
Interface *	PCI Express 4.0		
NVMe *	✓		
Memory type *	3D TLC NAND		
Component for *	Server/workstation		
Random read (4KB)	530000 IOPS		
Random write (4KB)	85000 IOPS		
Read latency	80 µs		
Write latency	15 µs		
Mean time between failures (MTBF)	2000000 h		
Power			
Power consumption (read)		10 W	
Power consumption (write)		7 W	
Weight & dimensions			
Width		70 mm	
Depth		100 mm	
Height		7 mm	
Weight		70 g	
Operational conditions			
Operating temperature (T-T)		0 - 70 °C	
Storage temperature (T-T)		-40 - 85 °C	
Non-operating shock		1500 G	
Maximum operating altitude		3050 m	



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